

Features

- ◆ **Highly Integrated MMIC**
 - ◊ Dual Path, Transmit/Receive Operation
 - ◊ 6-Bit Phase Shifter and 6-Bit Attenuator
 - ◊ Tx Gain = 21 dB; Rx Gain = 15 dB
 - ◊ Serial Control Data Input
- ◆ **50 Ω Input and Output Impedance**
- ◆ **Proven Manufacturability and Reliability**
 - ◊ No Airbridges
 - ◊ Polyimide Scratch Protection
 - ◊ No Hydrogen Poisoning Susceptibility

Description

The MAMF-000002-DIE000 is a 3-port, dual path transmit/ receive control MMIC. The on-chip serial-to-parallel converter enables the independent control of the 6-bit phase shifter and 6-bit attenuator and minimizes the required inputs. This product is fully matched to 50 ohms on both the input and output.

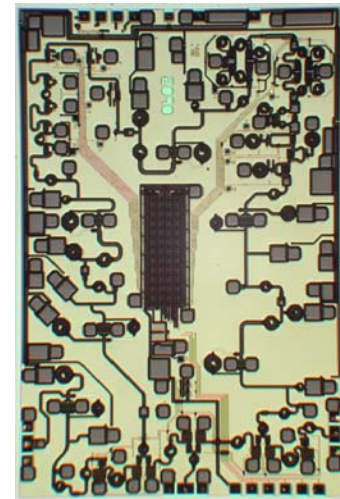
Fabricated using M/A-COM's repeatable, high performance and highly reliable GaAs Multifunction Self-Aligned Gate (MSAG) Process, each device is 100% RF tested on-wafer to ensure performance compliance.

M/A-COM's MSAG process features robust silicon-like manufacturing processes, planar processing of ion implanted transistors, multiple implant capability enabling power, low-noise, switch and digital FETs on a single chip, and polyimide scratch protection for ease of use with automated manufacturing processes. The use of refractory metals and the absence of platinum in the gate metal formulation prevents hydrogen poisoning when employed in hermetic packaging.

Maximum Operating Conditions¹

| Parameter | Symbol | Absolute Maximum | Units |
|---------------------------------------|--------------|------------------|-------|
| Tx Input Power | $T_x P_{IN}$ | 8 | dBm |
| Rx Input Power | $R_x P_{IN}$ | 11 | dBm |
| Drain Supply Voltage | V_{DD} | 12 | V |
| Gate Supply Voltage | V_{GG} | -6.0 | V |
| Quiescent Drain Current (No RF) | I_{DQ} | 500 | mA |
| Quiescent DC Power Dissipated (No RF) | P_{DISS} | 2.5 | W |
| Logic Supply Voltage | V_{EE} | -6.0 | V |
| Junction Temperature | T_J | 170 | °C |
| Storage Temperature | T_{STG} | -55 to +150 | °C |

1. Operation beyond these limits may result in permanent damage to the part.



Primary Applications

- ◆ Radar Systems
- ◆ Commercial Avionics

Control Chip, X-Band T/R
7.0—12.0 GHz

MAMF-000002-DIE000

Rev B
Preliminary Datasheet

Recommended Operating Conditions²

| Characteristic | Symbol | Min | Typ | Max | Unit |
|--------------------------|------------------|------|------|--------|------|
| Drain Supply Voltage | V _{DD} | 4.8 | 5.0 | 5.2 | V |
| Gate Supply Voltage | V _{GG} | -5.2 | -5.0 | -4.8 | V |
| Digital Supply Voltage | V _{EE} | -5.2 | -5.0 | -4.8 | V |
| Input Logic High Voltage | V _{IH} | 3.0 | 5.0 | 5.0 | V |
| Input Logic Low Voltage | V _{IL} | 0.0 | 0.0 | 0.4 | V |
| Clock Frequency | F _{CLK} | | 20 | | MHz |
| Thermal Resistance | Θ _{JC} | | 28.4 | | °C/W |
| MMIC Base Temperature | T _B | | | Note 3 | °C |

2. Operation outside of these ranges may reduce product reliability.

3. Maximum MMIC Base Temperature = 170°C — Θ_{JC} * V_{DD} * I_{DQ}

Electrical Characteristics: T_B = 25°C⁴, Z₀ = 50Ω, V_D = 5V, V_G = -5V, V_{EE} = -5V

| Parameter | Symbol | Typical | Units |
|--------------------------------|-----------------|-----------|-------|
| Bandwidth | f | 7.0-12.0 | GHz |
| Transmit Gain | G _n | 21 | dB |
| Receive Gain | G _n | 15 | dB |
| Input VSWR, Common Port, | VSWR | 1.5:1 | |
| Output VSWR, Tx Out Port, | VSWR | 1.7:1 | |
| Input VSWR, Rx In Port, Re- | VSWR | 1.7:1 | |
| Output VSWR, Common Port, | VSWR | 1.4:1 | |
| Transmit P1dB | P1dB | 22 | dBm |
| Receive P1dB | P1dB | 19 | dBm |
| Receive Third Order Intercept, | OTOI | 26 | dBm |
| Receive Noise Figure | NF | 10.5 | dB |
| Attenuator Range (6 bits, 64 | | 0 to 31.5 | dB |
| 0.5 dB Bit, Relative Gain, LSB | | -0.5 | dB |
| 1 dB Bit, Relative Gain | | -1.0 | dB |
| 2 dB Bit, Relative Gain | | -2.0 | dB |
| 4 dB Bit, Relative Gain | | -4.0 | dB |
| 8 dB Bit, Relative Gain | | -8.0 | dB |
| 16 dB Bit, Relative Gain, MSB | | -16.0 | dB |
| Phase Shifter Range (6 bits, | | 0 to 354 | ° |
| 5.6 ° Bit, Relative Phase, LSB | | -5.6 | ° |
| 11.2° Bit, Relative Phase | | -11.2 | ° |
| 22.5° Bit, Relative Phase | | -22.5 | ° |
| 45° Bit, Relative Phase | | -45 | ° |
| 90° Bit, Relative Phase | | -90 | ° |
| 180° Bit, Relative Phase, MSB | | -180 | ° |
| Gate Supply Current | I _{GG} | 10 | mA |
| Drain Supply Current | I _{DD} | 340 | mA |
| Logic Supply Current | I _{EE} | 50 | mA |

2 **4. T_B = MMIC Base Temperature**

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Visit www.macom.com for additional data sheets and product information.

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7.0–12.0 GHz

MAMF-000002-DIE000

Rev B
Preliminary Datasheet

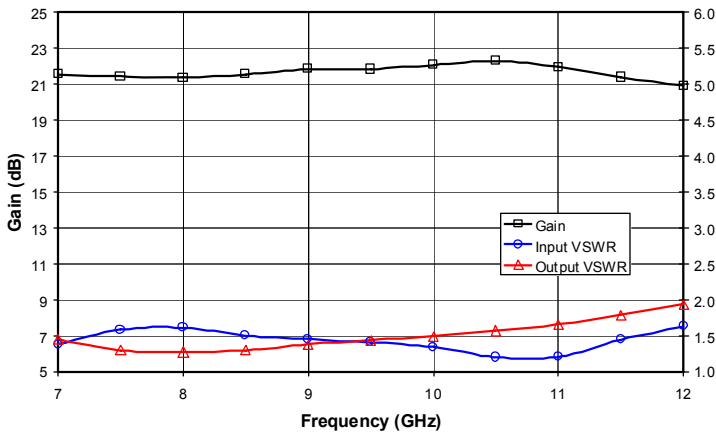


Figure 1. Transmit S-Parameters

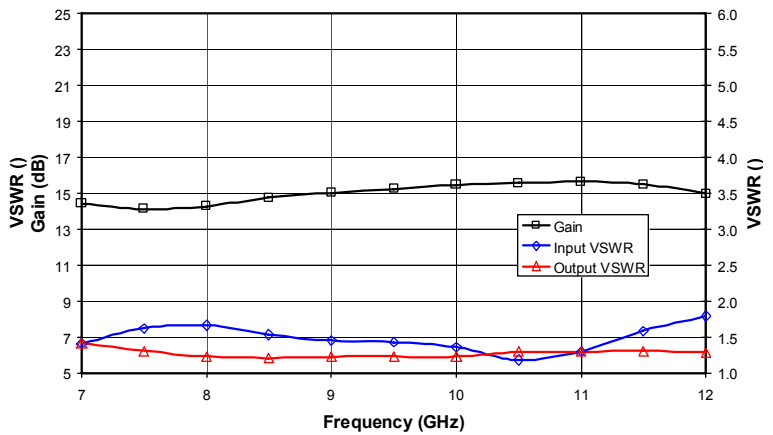


Figure 2. Receive S-Parameters

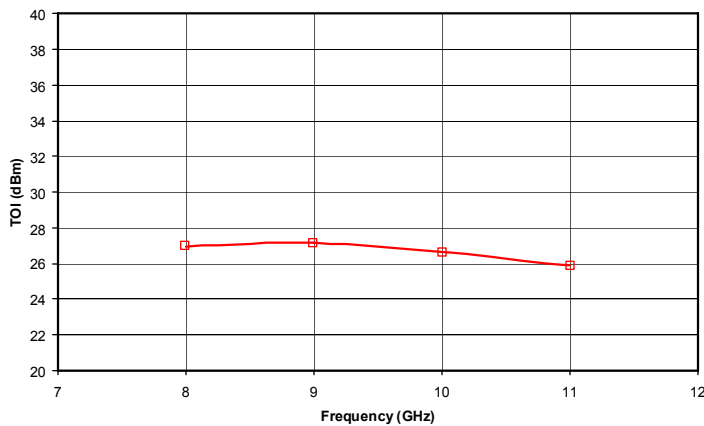


Figure 3. Receive Output TOI

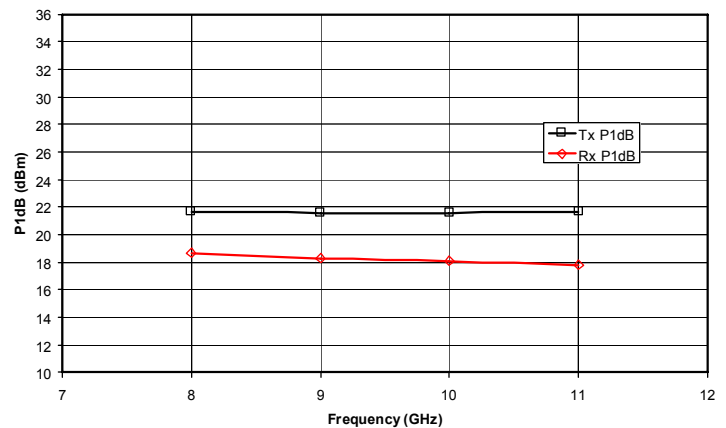


Figure 4. Transmit and Receive P1dB

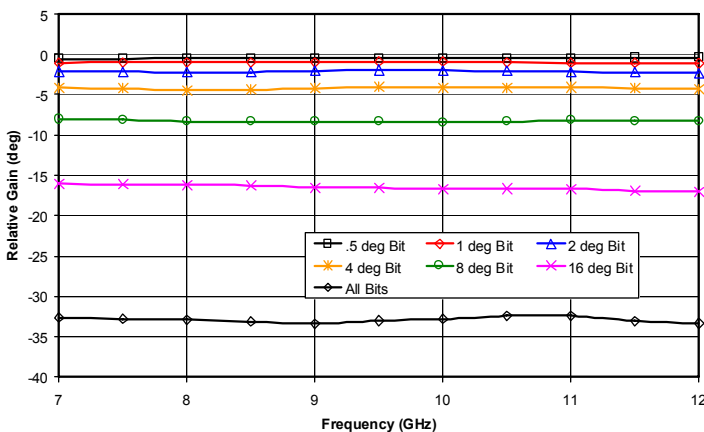


Figure 5. Relative Gain of Major Attenuator States

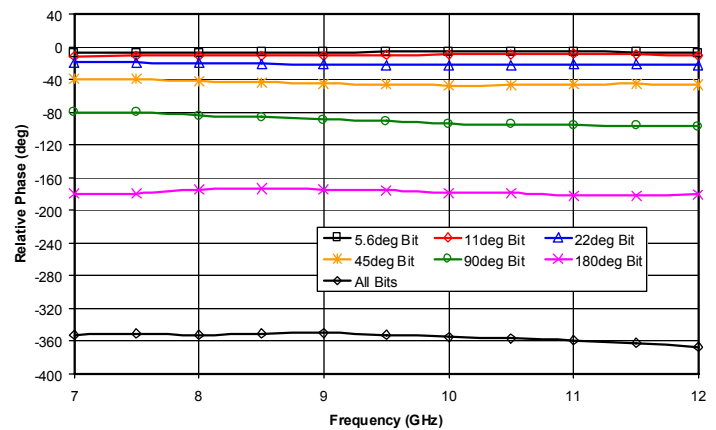


Figure 6. Relative Phase of Major Phase Shifter States

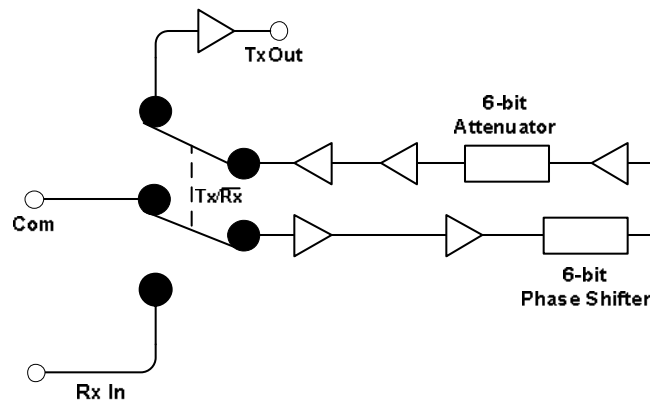


Figure 7. Block Diagram of Transmit/Receive Control MMIC

Truth Table and Data Sequence

| X-Band T/R MMIC Control Function | | |
|----------------------------------|--------------|---|
| INPUT SIGNAL | LOGIC LEVEL | FUNCTION |
| CK (Clock) | Falling Edge | Shifts the data, DI |
| DI (Data In) | High/Low | Phase and Attn Setting |
| LD (Load) | Falling Edge | Loads the data from D24 Shift Register |
| SL and TR (Select & T/R Control) | Low | Selects odd bits (Transmit) and Transmit Path |
| SL and TR (Select & T/R Control) | High | Selects even bits (Receive) and Receive Path |
| Logic Level | Logic High | Logic 1: 3.0 to 5V |
| | Logic Low | Logic 0: 0 to 0.4V |
| Attn and Phase States | Logic Low | Phase and Attn in Ref. State |
| | Logic High | Phase and Attn Shift Negative |

LSB data enters first and MSB enters last. LSB data travels all 24 shift registers.

| Serial-to-Parallel Converter I/Os | | | | | | |
|-----------------------------------|---------------------------------|----------------|--|-------------------|---------------------------------|-----------------|
| Input Data to SPC | TR "Low" – TX TR "High" – RX | Phase and Attn | | Input Data to SPC | TR "Low" – TX TR "High" – RX | Phase and Attn |
| D1-LSB | Transmit | 5.6°-bit PS | | D13 | Transmit | 0.5 dB-bit Attn |
| D2 | Receive | | | D13 | Receive | |
| D3 | Transmit | 11°-bit PS | | D15 | Transmit | 1 dB-bit Attn |
| D4 | Receive | | | D16 | Receive | |
| D5 | Transmit | 22°-bit PS | | D17 | Transmit | 2 dB-bit Attn |
| D6 | Receive | | | D18 | Receive | |
| D7 | Transmit | 45°-bit PS | | D19 | Transmit | 4 dB-bit Attn |
| D8 | Receive | | | D20 | Receive | |
| D9 | Transmit | 90°-bit PS | | D21 | Transmit | 8 dB-bit Attn |
| D10 | Receive | | | D22 | Receive | |
| D11 | Transmit | 180°-bit PS | | D23 | Transmit | 16 dB-bit Attn |
| D12 | Receive | | | D24 | Receive | |

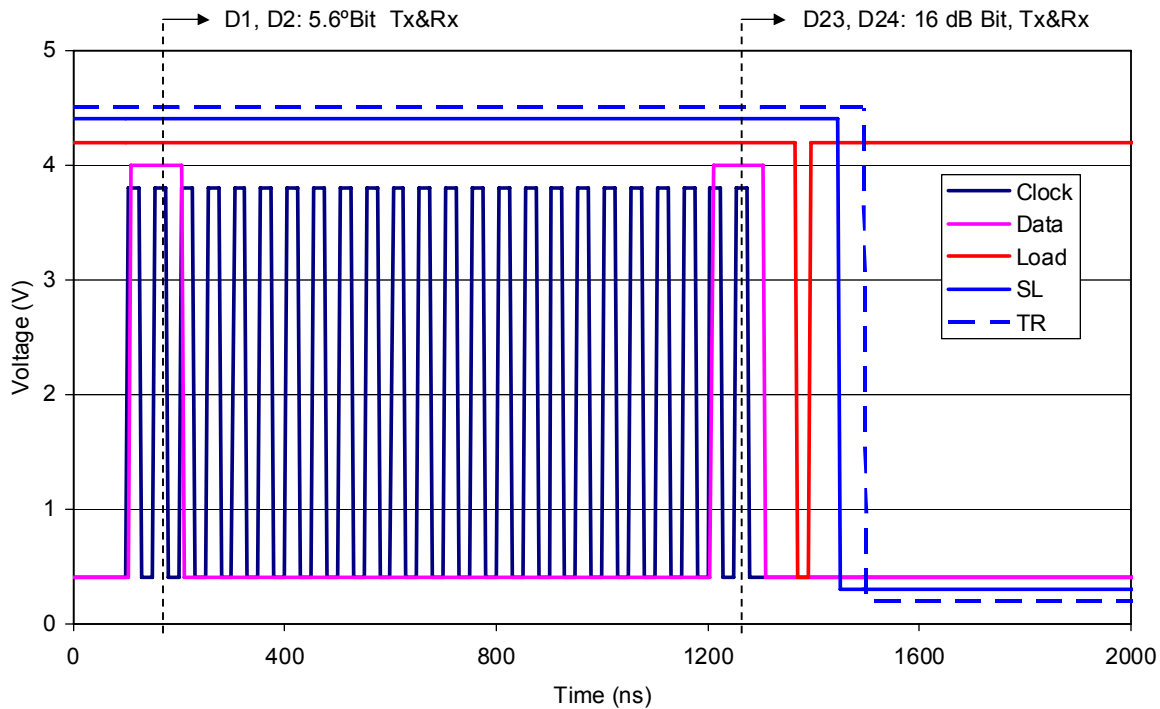


Figure 8. Timing Diagram, Data Sequence

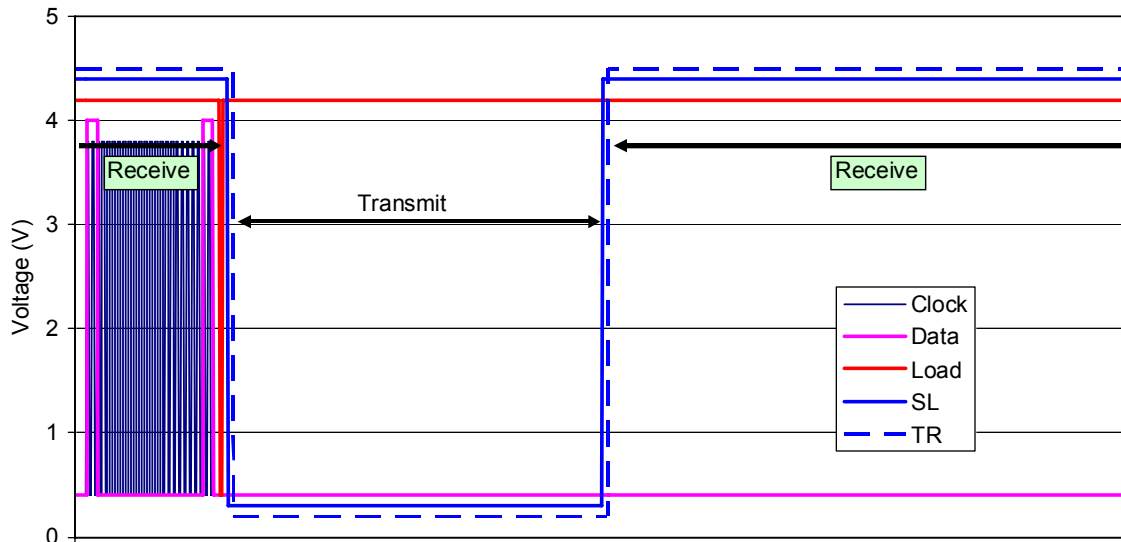


Figure 9. Timing Diagram, Transmit/Receive Relationship

Mechanical Information

Chip Size: 6.0 x 4.0 x 0.075 mm (236 x 157 x 3 mils)

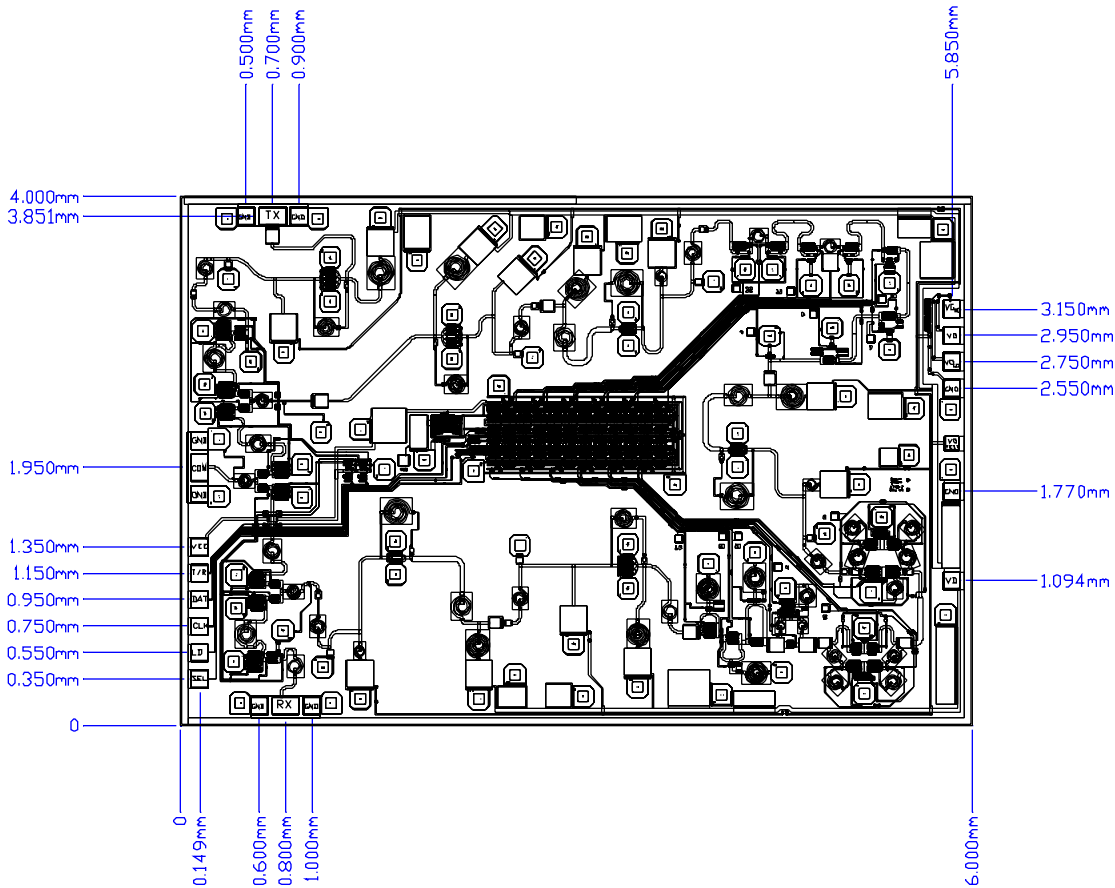


Figure 10 . Die Layout

Bond Pad Information

| Pad | Type | Nominal Voltage | Size | |
|--|---------|-----------------|-------------------|--------|
| | | | (μm) | (mils) |
| Common, Tx Out, Rx In | RF | N/A | 150 x 150 | 6 x 6 |
| T/R, Sel, Load, Data, Clock | Control | 0 / 5 V | 125 x 125 | 5 x 5 |
| V _{DD} | DC | 5.0 V | 150 x 150 | 6 x 6 |
| V _{EE} | DC | -5.0 V | 125 x 125 | 5 x 5 |
| V _{G-HI} , V _{G-N} , V _{G-LO} | DC | -5.0 V | 150 x 150 | 6 x 6 |

Assembly and Bonding Diagram

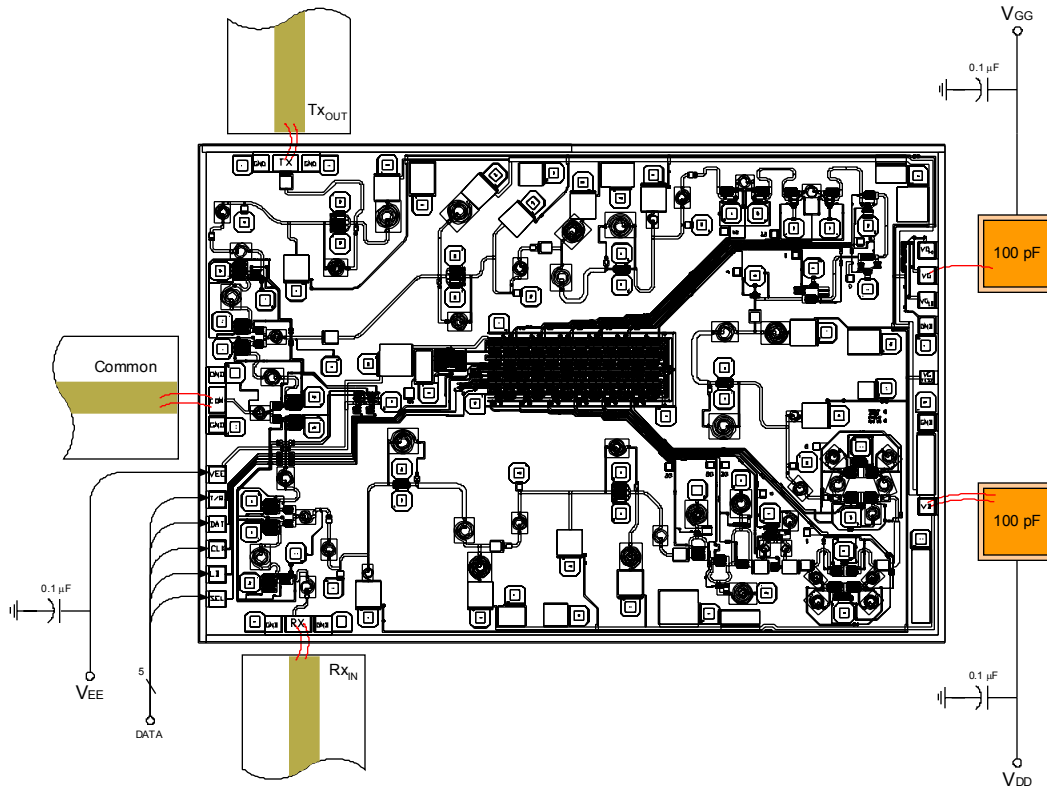


Figure 11. Recommended bonding diagram.
Support circuitry typical of MMIC characterization fixture for CW testing.

Assembly Instructions:

Die attach: Use AuSn (80/20) 1 mil. preform solder. Limit time @ 300 °C to less than 5 minutes.

Wirebonding: Bond @ 160 °C using standard ball or thermal compression wedge bond techniques. For DC pad connections, use either ball or wedge bonds. For best RF performance, use wedge bonds of shortest length, although ball bonds are also acceptable.

Biasing Note: Must apply negative bias to V_{GG} before applying positive bias to V_{DD} to prevent damage to amplifier.

Operating Instructions

This device is static sensitive. Please handle with care. To operate the device, follow these steps.

1. Apply $V_{GG} = -5$ V, $V_{EE} = -5$ V, $V_{DD} = 0$ V.
2. Ramp V_{DD} to desired voltage, typically 5 V.
3. Adjust V_{GG} to set I_{DQ} .
4. Set RF input.
5. Power down in reverse. Turn V_{GG} off last.

